

# Acrylic Adhesive

## Acrylic series



It features fast curing, a low shrinkage ratio, and excellent thermal conductivity. Suitable for the adhesion to low surface energy plastics and metallic substrates.

Product number	Color	Viscosity (cps)	Ratio (A : B)	Curing parameters	Shear strength (kgf/cm <sup>2</sup> )	Thermal conductivity (W/m·K)
KA007	A: Ash gray	A: 70,000~80,000	10 : 1	25°C / 24~48hrs or 60°C / 30~60mins	Steel vs. Steel, 140	0.81
	B: Ash gray	B: 15,000~25,000				

\*The above values are for reference only. The actual value based on TDS.

# Thermally Conductive Grease



The thermally conductive grease is used to fill the irregular gaps between the heat source and thermal module. By increasing the heat transfer area, the heat can be quickly transferred to the thermal module and improve the heat dissipation performance and extend the product service life. Everwide thermal grease features long-term stability, high-temperature resistance, low volatilization, no overflow, and easy to rework.

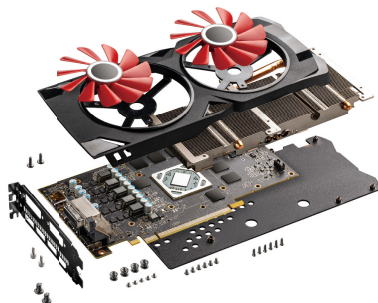
## Silicone thermal grease

Product number	Color	Viscosity (cps)	Operating temperature	Thermal conductivity (W/m·K)	Storage
JA447-6	White	1,500,000~3,500,000	-40~180°C	2.5	Store in a refrigerated place
JA447-8	White	-	-40~180°C	2.8	Store in a refrigerated place
JA447-15	White	420,000	-40~180°C	4	Store in a refrigerated place
JC922-1	Gray	1,500,000~4,000,000	-40~180°C	3.2	Store in a refrigerated place

## Non-silicone thermally conductive grease

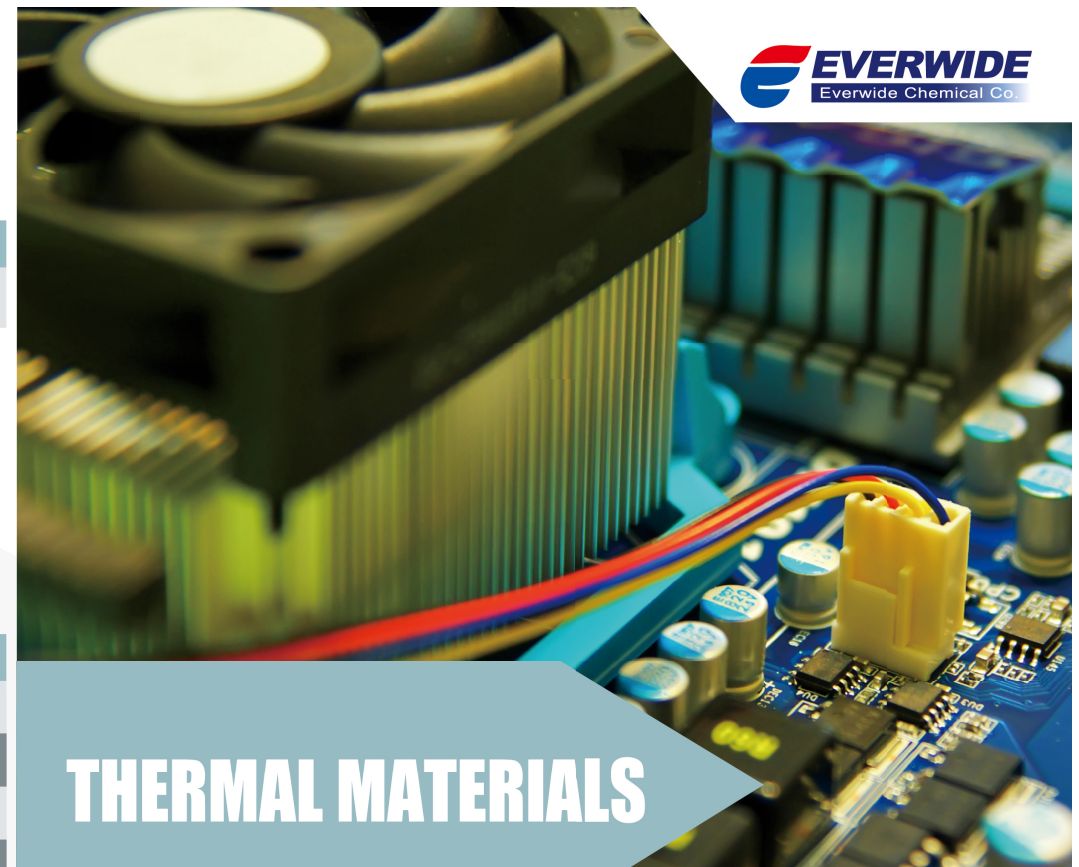
Product number	Color	Viscosity (cps)	Operating temperature	Thermal conductivity (W/m·K)	Storage	Features
JD655-1	White	250,000~376,000	-40~200°C	1.3	Store in a refrigerated place	Water washable

\*The above values are for reference only. The actual value based on TDS.

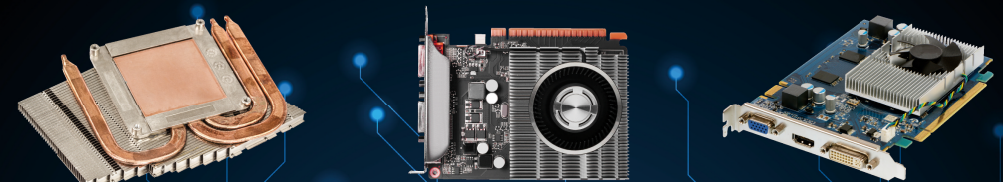


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# THERMAL MATERIALS



## Thermally Conductive Adhesive

It can endure thermal expansion and stress change without removal or separation for a long time. The product of Everwide, mainly applied to various components and modules requiring adhesion and thermal conductivity, can still maintain their adhesion and thermal conductivity even under strict operation and test conditions.

Everwide “Glue” the world

# Epoxy

## Two-component thermally conductive adhesives

Two-component thermal resin series was developed especially for the adhesion and thermal conductivity of electronic heating components and cooling fins. The product can apply to various processes requiring different viscosities, time, and thermal conductivity by varied mixing ratios. This series features excellent thermal conductivity, adhesion, insulation, and a low shrinkage ratio. It can pass severe thermal impact tests and maintain outstanding thermal conductivity even after long-term usage.

Product number	Color	Viscosity (cps)	Ratio (A : B)	Curing parameters	Shear strength (kgf/cm <sup>2</sup> )	Tg(°C)	Thermal conductivity (W/m·K)
JD173-2	A: Gray B: White	A: 80,000~140,000 B: 130,000~230,000	2 : 1	25°C / 7days or 80°C / 1hr	Al vs. Al, 259	44°C	2
JD173-3	A: Gray B: White	A: 9,000~16,000 B: 30,000~60,000	2 : 1	25°C / 7days or 80°C / 1hr	Al vs. Al, 297	46°C	1

Product number	Color	Viscosity (cps)	Ratio (A : B)	Curing parameters	Hardness (Shore D)	Tg(°C)	Thermal conductivity (W/m·K)
JA293-2	A: Black B: Clear	A: 55,000~85,000 B: <100	100 : 8	25°C / 5~7days or 80°C / 2hrs	84	41°C	1
JD867	A: Black B: Clear	A: 40,000~80,000 B: <120	10 : 1	80°C / 3hrs	88	45°C	2



## One-component thermally conductive adhesive

One-component thermally conductive hardens the resin quickly and reduces the process time through heating. The features are high thermal conductivity, high Tg, low-temperature curing, and fast curing. This series not only possesses excellent thermal conductivity, adhesion, insulation, and a low shrinkage ratio but also pass severe environmental tests.

Product number	Color	Viscosity (cps)	Curing parameters	Shear strength (kgf/cm <sup>2</sup> )	Tg(°C)	Thermal conductivity (W/m·K)
JB688-28	Gray	380,000~580,000	150°C / 30mins	Cu vs. cast aluminum, 258	99°C	3
JC953-1	White	178,000~267,000	150°C / 30mins	Cu vs. cast aluminum, 252	68°C	1.54

# Thermally Conductive Silicone

## One-component thermally conductive modified silicone

One component thermally conductive modified silicone series was developed especially for the adhesion and thermal conductivity of electronic materials. To meet the demands of a simple process, this series enables excellent adhesion and thermal conductivity through moisture curing reaction, curing can be achieved at room temperature. Products featuring superior insulation and a low shrinkage/expansion ratio not only pass severe thermal shock tests but also maintain outstanding adhesion and thermal conductivity after long-term use.

Product number	Color	Viscosity (cps)	Hardness (Shore A)	Thermal conductivity (W/m·K)	Features
FS198BL1	Black	100,000~200,000	83	2	Excellent adhesion, flowable
FS198W1	White	100,000~200,000	83	2	Excellent adhesion, (Ti>3)
FS132BL83	Black	50,000~100,000	90	2	High adhesion & hardness, flowable, tin-free
FS132BL84	Black	80,000~160,000	90	2	High adhesion & hardness, (Ti>3), tin-free
FS168W60	White	50,000~120,000	76	1.7	Low viscosity, excellent fluidity, compliant with UL 94 V-0 flammability standard

## Two-component thermally conductive silicone

Two-component thermally conductive silicone series is designed for the adhesion and thermal conductivity of electronic materials. To meet the fast process's demands, the user can mix the AB glue then the curing can be achieved at room temperature. This process can be accelerated by heating. After curing, besides full curing properties and outstanding thermal conductivity, the applied product also features a wide operating temperature, low water absorption, excellent insulation and low shrinkage/expansion ratio. It can pass severe thermal shock tests and maintain superior physical properties after long-term use.

Product number	Color	Viscosity (cps)	Hardness (Shore A)	Operating temperature	Thermal conductivity (W/m·K)	Features
FX176BL	Black	30,000~60,000	50	-40~200°C	2	Addition silicone rubber, A:B=1:1, flowable, room temperature curing or heating & curing, applicable to deep filling, can adhere to metal/ceramic/glass, low water absorption
FX176W	White	30,000~60,000	50	-40~200°C	2	
FX176BL1	Black	30,000~60,000	50	-40~200°C	2	Addition silicone rubber, A:B=1:1, flowable, room temperature curing or heating & curing, adhesion-free, can be completely removed during the rework, low water absorption
FX176W1	White	30,000~60,000	50	-40~200°C	2	
FX177BL	Black	30,000~60,000	50	-40~200°C	2	Condensation silicone rubber, A:B=5:1, flowable, moisture curing, applicable to deep filling, can adhere to various materials, low water absorption
FX177W	White	30,000~60,000	50	-40~200°C	2	



## One-component thermally conductive dealcoholized silicone

One-component thermally conductive dealcoholized silicone series is designed for the adhesion and thermal conductivity of electronic materials. To meet the simple process's demands, this series possesses excellent adhesion and thermal conductivity through moisture curing. Curing can be achieved at room temperature. After curing, besides full curing and outstanding thermal conductivity, the applied product also features a wide operating temperature, low water absorption, excellent insulation, and low shrinkage/expansion ratio. It can pass severe thermal shock tests, maintain superior adhesion, and thermal conductivity after long-term use.

Product number	Color	Viscosity (cps)	Hardness (Shore A)	Operating temperature	Thermal conductivity (W/m·K)	Features
FX196BL	Black	50,000~100,000	50	-40~200°C	2	Excellent adhesion, flowable, low water absorption
FX196W	White	50,000~100,000	50	-40~200°C	2	
FX196BL1	Black	80,000~160,000	50	-40~200°C	2	Excellent adhesion, (Ti>3), low water absorption
FX196W1	White	80,000~160,000	50	-40~200°C	2	

## One-component thermally conductive HTV silicone

One-component thermally conductive HTV silicone series is designed for the adhesion and thermal conductivity of electronic materials. To meet the demands of a fast process, this series is suitable for heating. After curing, besides excellent thermal conductivity, the applied product also features a wide operating temperature range, low water absorption, excellent insulation, and low shrinkage/expansion ratio. It can pass severe thermal shock tests, maintain superior adhesion and thermal conductivity after long-term use.

Product number	Color	Viscosity (cps)	Hardness (Shore A)	Operating temperature	Thermal conductivity (W/m·K)	Features
FX172G	Gray	30,000~60,000	90	-40~200°C	2	Flowable, applicable to deep filling. It has excellent adhesion (Al vs. Al=55kgf/cm <sup>2</sup> ) and low water absorption. It needs to be heated at 150°C for 30 minutes and should be stored in a refrigerated place
FX172G1	Gray	30,000~60,000	90	-40~200°C	2	(Ti>3), applicable to deep filling. It has excellent adhesion (Al vs. Al=55kgf/cm <sup>2</sup> ) and low water absorption. It needs to be heated at 150°C for 30 minutes and should be stored in a refrigerated place
FX172BL2	Black	30,000~60,000	90	-40~200°C	2	(Ti>3), applicable to deep filling. It is adhesion-free and can be completely removed during the rework. It has low water absorption, needs to be heated at 120°C for 30 minutes, and should be stored in a refrigerated place
FX172W2	White	30,000~60,000	90	-40~200°C	2	